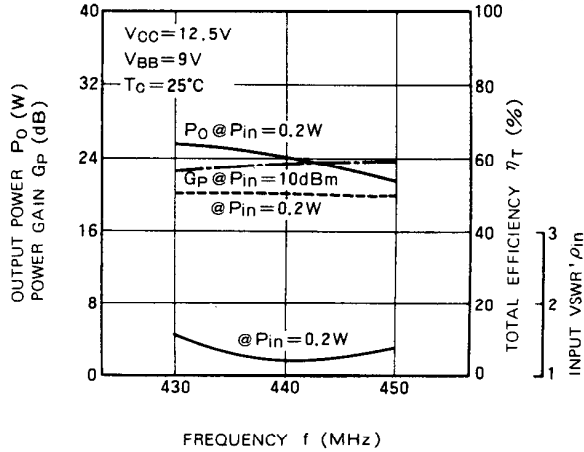
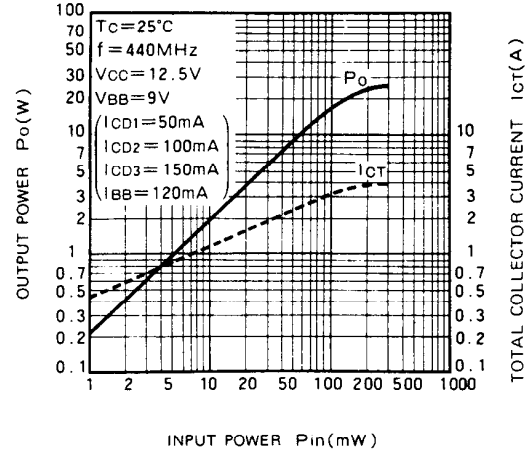


TYPICAL PERFORMANCE DATA

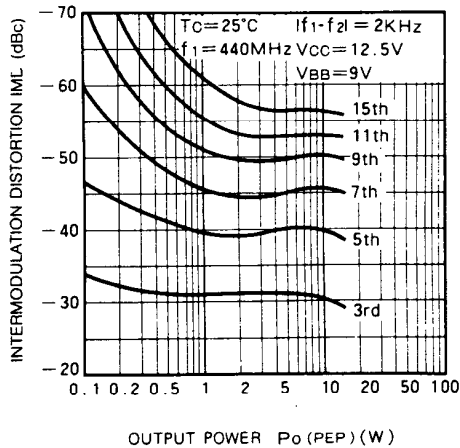
OUTPUT POWER, POWER GAIN, TOTAL EFFICIENCY, INPUT VSWR VS. FREQUENCY CHARACTERISTICS (M57716)



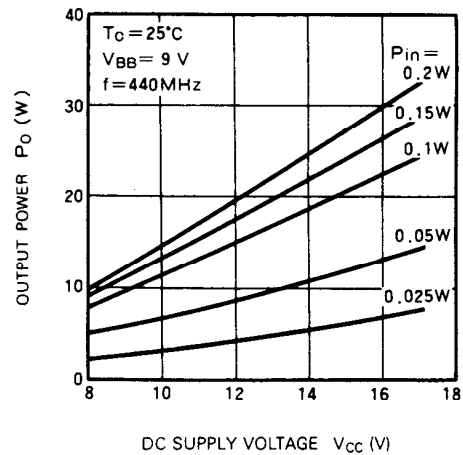
OUTPUT POWER, TOTAL COLLECTOR CURRENT VS. INPUT POWER



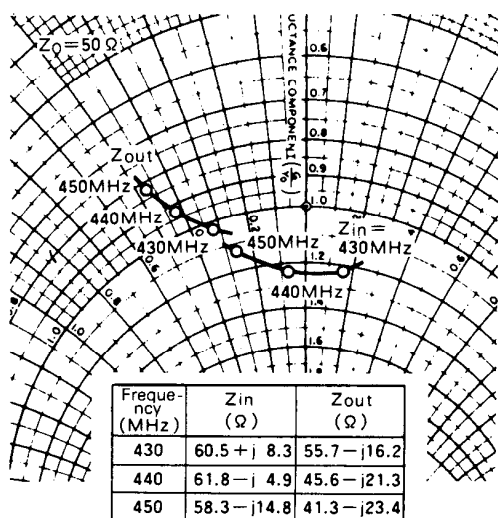
INTERMODULATION DISTORTION VS. OUTPUT POWER



OUTPUT POWER VS. DC SUPPLY VOLTAGE



INPUT IMPEDANCE, OUTPUT IMPEDANCE VS. FREQUENCY



Test condition : $V_{CC}=12.5V$, $V_{BB}=9V$
 $P_{in}=0.2W$

DESIGN CONSIDERATION OF HEAT RADIATION.

Please refer to following consideration when designing heat sink.

1. Junction temperature of incorporated transistors at standard operation.

(1) Thermal resistance between junction and package of incorporated transistors.

a) First stage transistor

$$R_{th(j-c)1} = 15^{\circ}C/W \text{ (Typ.)}$$

b) Second stage transistor

$$R_{th(j-c)2} = 6^{\circ}C/W \text{ (Typ.)}$$

c) Final stage transistor

$$R_{th(j-c)3} = 2^{\circ}C/W \text{ (Typ.)}$$

(2) Junction temperature of incorporated transistors at standard operation.

- Conditions for standard operation.

$P_O = 14W$, $V_{CC} = 12.5V$, $P_{in} = 80mW$, $\eta_T = 35\%$ (minimum rating), P_{O1} (Note 1) = $1W$, P_{O2} (2) = $4.5W$, $I_T = 3.2A$ (I_{T1} (3) = $0.15A$, I_{T2} (4) = $0.55A$, I_{T3} (5) = $2.5A$)

Note 1: Output power of the first stage transistor

Note 2: Output power of the second stage transistor

Note 3: Circuit current of the first stage transistor

Note 4: Circuit current of the second stage transistor

Note 5: Circuit current of the final stage transistor

- Junction temperature of the first stage transistor

$$T_{j1} = (V_{CC} \times I_{T1} - P_{O1} + P_{in}) \times R_{th(j-c)1} + T_c^{(6)}$$

$$= (12.5 \times 0.15 - 1 + 0.08) \times 15 + T_c$$

$$= 14.4 + T_c (^{\circ}C)$$

Note 6: Package temperature of device

- Junction temperature of the second stage transistor

$$T_{j2} = (V_{CC} \times I_{T2} - P_{O2} + P_{O1}) \times R_{th(j-c)2} + T_c$$

$$= (12.5 \times 0.55 - 4.5 + 1) \times 6 + T_c$$

$$= 20.3 + T_c (^{\circ}C)$$

- Junction temperature of the final stage transistor

$$T_{j3} = (V_{CC} \times I_{T3} - P_O + P_{O2}) \times R_{th(j-c)3} + T_c$$

$$= (12.5 \times 2.5 - 14 + 4.5) \times 2 + T_c$$

$$= 43.5 + T_c (^{\circ}C)$$

2. Heat sink design

In thermal design of heat sink, try to keep the package temperature at the upper limit of the operating ambient temperature (normally $T_a = 60^{\circ}C$) and at the output power of $14W$ below $90^{\circ}C$.

The thermal resistance $R_{th(c-a)}$ (7) of the heat sink to realize this:

$$\text{Note 7: } R_{th(c-a)} = \frac{T_c - T_a}{(P_O/\eta_T) - P_O + P_{in}} = \frac{90 - 60}{(14/0.35) - 14 + 0.08}$$

$$= 1.15 (^{\circ}C/W)$$

Note 7: Inclusive of the contact thermal resistance between device and heat sink.

Mounting the heat sink of the above thermal resistance on the device,

$$T_{j1} = 104.4^{\circ}C, T_{j2} = 110.3^{\circ}C, T_{j3} = 133.5^{\circ}C \text{ at } T_a = 60^{\circ}C, T_c = 90^{\circ}C.$$

In the annual average of ambient temperature is $30^{\circ}C$,

$$T_{j1} = 74.4^{\circ}C, T_{j2} = 80.3^{\circ}C, T_{j3} = 103.5^{\circ}C.$$

As the maximum junction temperature of these incorporated transistors T_{jmax} are $175^{\circ}C$, application under fully derated condition is ensured.